



## Education and R&D oriented, Manual Flip-Chip Bonder 3 $\mu\text{m}$

The **ACCURA M** is a manual flip-chip bonder that allows  $\pm 3 \mu\text{m}$  accuracy. This equipment permits to align manually the components with a high level of precision.

The motorized arm controls precisely the bonding force. Combining and synchronizing the arm with the temperature controller, it guarantees a perfect quality and high repeatability of your process.

The **ACCURA M**, more than a pick-and-place system, offers thermocompression and reflow capabilities. It is the perfect equipment for universities and R&D institutes.

## Applications

- Flip-chip, die attach
- Chip-to-chip, chip-to-substrate
- Laser diode, laser bar
- VCSEL, photodiode
- LED
- Micro assembly
- MEMS, MOEMS, MCM

## Highlights

- **Accuracy\***  $\pm 3 \mu\text{m}$
- **Process controlled thanks to closed loop systems**
- **Easy to use**
- **Granite structure offering high stiffness**
- **Vertical arm avoiding lateral shift during bonding**
- **Very small footprint on open platform**

\*depending on configuration and application.



## User benefits

- Open platform with simple user interface on touchscreen
- Quick start for new applications
- Superimposed images for easy manual alignment
- Bonding controlled by the machine to guarantee a high repeatability from sample to sample.

## Main bonding processes

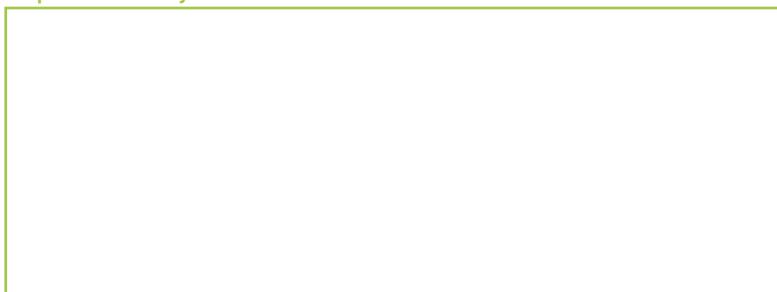
- Flip-chip bonding
- Die bonding
- Pick-and-place
- Thermocompression
- Reflow
- UV curing
- Gold, Gold/Tin, Indium, Copper

## Specifications

Machine	Bonding heads	
Footprint:	900 x 550 mm	Sq. 22 mm
Height:	650 mm	Sq. 22 mm, 400°C
Weight:	~110 kg	80 mW / cm <sup>2</sup> @ 365 nm
Component size	Substrate chuck	
Chip (Upper die)	0.2 x 0.2 - 22 x 22 mm	
Substrate (Lower die)	0.2 x 0.2 - 100 x 100 mm	
Total thickness	0.05 to 7 mm	
Bonding arm	Optics	
Accuracy*	± 3 µm	
Z resolution	0.01 µm	
Force*	Low force: 0.2 to 10 N High force: 1 to 200 N	
Alignment stage	Options	
XY stage	Digital camera resolution	
Theta travel	2 sight cameras 0.4 µm/pixel	
Field of view	800 x 600 µm	
Data, design and specifications depend on individual process conditions and can vary according to equipment configurations. Not all specifications may be valid simultaneously. Illustrations, photos and specifications in this datasheet are not legally binding. Specifications are subject to change without prior notice.	Dispenser	
	XY high resolution alignment stage, resolution 1 µm	
	UV Curing system	
	Process recording	Frame with elastomeric insulators
	Frame with elastomeric insulators	Wafer frame up to Ø200 mm

\*depending on configuration and application.

Represented by:



### SET Corporation S.A.

Smart Equipment Technology

131 impasse Barteudet  
74490 Saint-Jeoire - France  

- Ph: +33 (0)450 35 83 92
- Fax: +33 (0)450 35 88 01
- Email: info@set-sas.fr

[www.set-sas.fr](http://www.set-sas.fr)